Product/Process Change Notice - PCN 20_0223 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: OP07 Die Revision, Wafer Fabrication Site Transfer & Process Change

Publication Date: 22-Jul-2020

Effectivity Date: 24-Oct-2020 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:
Initial Release.

Description Of Change:

1) Wafer fabrication site transfer from Analog Devices, USA to Analog Devices, Ireland.
2) Wafer fabrication process change from BIPOLAR to iPOLAR.
3) Layout has been revised to accommodate the fabrication process change. This includes the transistor layout, rerouting of circuitry and bond pad location.
4) Polyimide thickness is increasing from 17um to 18um

Reason For Change:

Migrating the OP07 to a newer process to improve capacity utilization to ensure longevity of the supply chain.

Impact of the change (positive or negative) on fit, form, function & reliability:

The new material will meet or exceed the performance of the existing material. There will be no changes to form, fit, function and reliability.

Product Identification *(this section will describe how to identify the changed material)*

Cut-Over Date Code provided upon request.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_20_0223_Rev_-_OP07_Qualification_Results_Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.			
Americas:	**Europe:**	**Japan:**	**Rest of Asia:**
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (3)				
OP07 / OP07CSZ	OP07 / OP07CSZ-REEL	OP07 / OP07CSZ-REEL7		

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	22-Jul-2020	24-Oct-2020	Initial Release.

OP07 Die Revision, Wafer Fabrication Site & Process Change

Qualification Results Summary of OP07 Die Revision, Wafer Fabrication Site & Process Change

QUALIFICATION PLAN / STATUS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Early Life Failure Rate (ELFR)	MIL-STD-883, M1015	4 x 500	Pass
High Temperature Operating Life (HTOL)	JEDEC *JESD22-A108*	3 x 77	Pass
Highly Accelerated Stress Test (HAST)[1]	JEDEC *JESD22-A110*	3 x 77	Pass
Solder Heat Resistance (SHR)[1]	JEDEC *J-STD-020*	1 x 30	Pass
Temperature Cycle (TC)[1]	JEDEC *JESD22-A104*	1 x 77	Pass
Unbiased Highly Accelerated Stress Test (UHAST)[1]	JEDEC *JESD22-A118*	1 x 77	Pass
Latch-Up	JEDEC *JESD78*	3/test	Pass ±200 mA, ±22.5 V
Electrostatic Discharge *Human Body Model*[2]	ESDA/JEDEC *JS-001-2011*	3/voltage	Pass ±2000 V
Electrostatic Discharge *Field-Induced Charged Device Model*	JEDEC *JESD22-A114*	3/voltage	Pass ±1250 V

[1] Preconditioned per JEDEC J-STD-020 Level 1

[2] HBM testing shows the OP07 passes at all level between 750 V and 2 kV, but failures occur at 500 V.